



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC150N03LD G	Issued	24. June 2021
MA#	MA000359618		
Package	PG-TDSON-8-4	Weight*	95.79 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.562	0.59	0.59	5864	5864
chip_2	inorganic material	silicon	7440-21-3	0.562	0.59	0.59	5864	5864
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		139	
	non noble metal	iron	7439-89-6	0.044	0.05		464	
	non noble metal	copper	7440-50-8	44.409	46.33	46.39	463593	464196
wire	non noble metal	aluminium	7429-90-5	0.561	0.59	0.59	5854	5854
encapsulation	organic material	carbon black	1333-86-4	0.093	0.10		967	
	plastics	epoxy resin	-	6.574	6.86		68623	
	inorganic material	silicondioxide	60676-86-0	39.627	41.37	48.33	413671	483261
leadfinish	non noble metal	tin	7440-31-5	1.308	1.37	1.37	13651	13651
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	501	502
solder	non noble metal	tin	7440-31-5	0.035	0.04		365	
	noble metal	silver	7440-22-4	0.044	0.05		456	
	non noble metal	lead	7439-92-1	1.669	1.74	1.83	17426	18247
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.245	0.26	0.26	2557	2561
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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